



VMDSEMI

VUTA003R024NA

Datasheet



VMDSEMI

General Description
Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
30V	2.4mΩ@10V	165A
	3.5mΩ@4.5V	

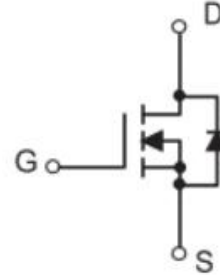
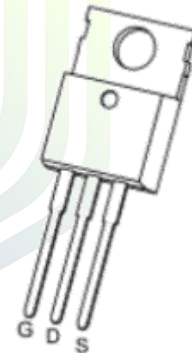


Figure 1 Symbol of VUTA003R024NA

Features

- Trench Technology Power MOSFET
- Low Gate Charge
- Low Gate Resistance
- Low $R_{DS(ON)}$
- 100% UIS Tested

Package Type

TO-220-3L-C
Application

- Power Switch Application
- DC/DC Converter

Figure 2 Package Type of VUTA003R024NA

Ordering Information

Product Name	Package
VUTA003R024NA	TO-220-3L-C

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	165	A
Pulsed Drain Current ^{Note2}	I_{DM}	660	
Avalanche Current ^{Note3}	I_{AS}	64	A
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	1024	mJ
Total Power Dissipation ^{Note5}	P_D	108	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		1.15		°C/W



Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	3.0	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(ON)}$	$V_{GS}=10V, I_D=30A$		1.8	2.4	mΩ
		$V_{GS}=4.5V, I_D=10A$		2.4	3.5	
Forward Transconductance ^{Note4}	g_{FS}	$V_{DS}=10V, I_D=20A$	10			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=15V$		7449		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		1201		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		1091		pF
Total Gate Charge	Q_g	$V_{DS}=15V$		147.7		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		19.5		
Gate-Drain Charge	Q_{gd}	$I_D=10A$		29.0		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		1.67		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=20V$		26		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		24		
Turn-off Delay Time	$t_{d(off)}$	$R_L=15\Omega$		91		
Turn-off Fall Time	t_f	$R_G=2.5\Omega$		39		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=10A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD}=15V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$ Starting $T_J=25^\circ C$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)}=150^\circ C$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$.

Typical Performance Characteristics

Figure 3: Transfer Characteristics

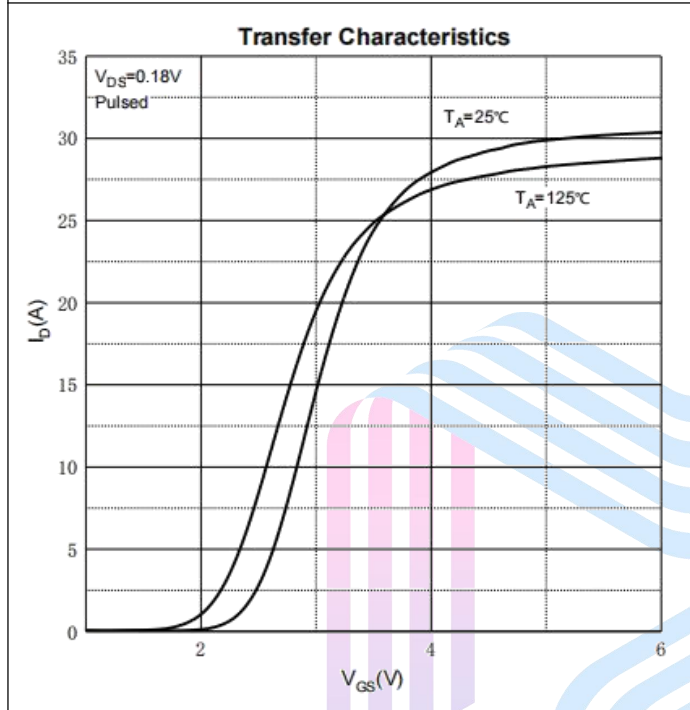


Figure 4: Output Characteristics

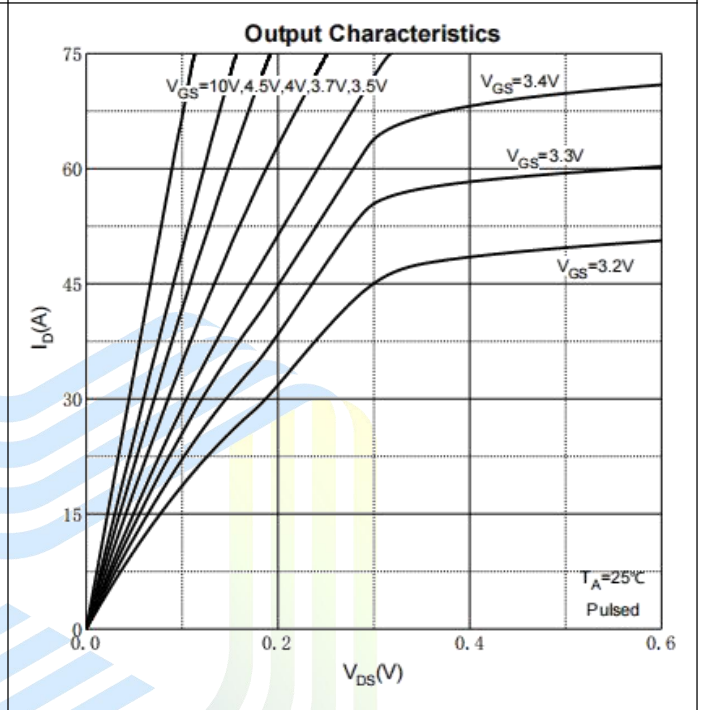


Figure 5: On-Resistance vs. Drain Current

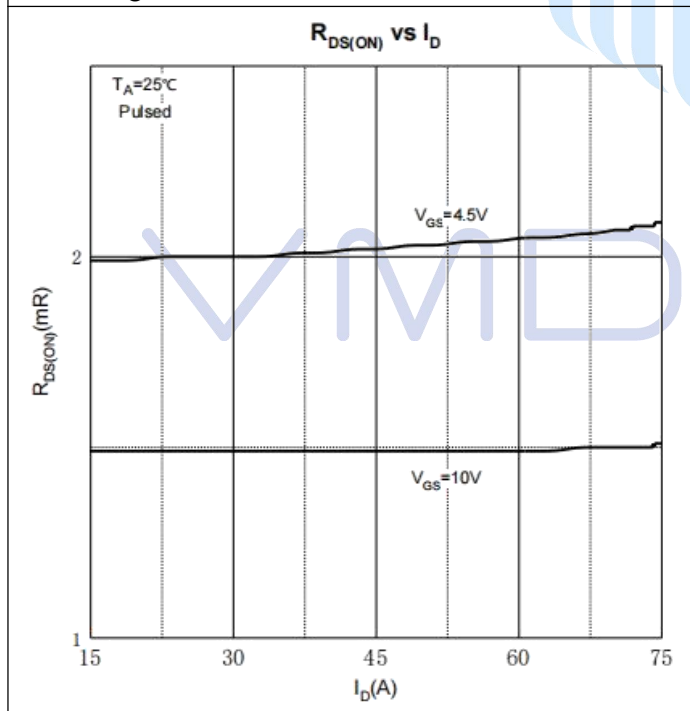


Figure 6: On-Resistance vs. Gate Voltage

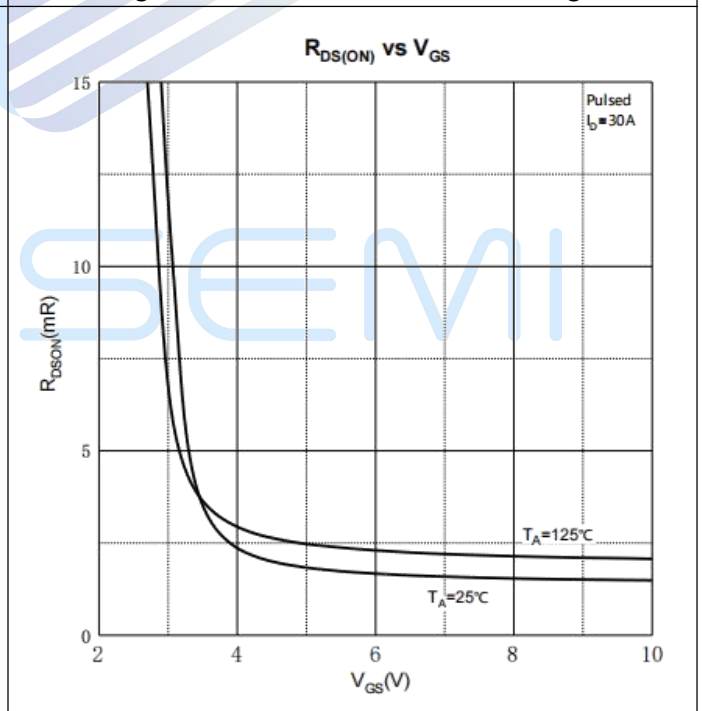


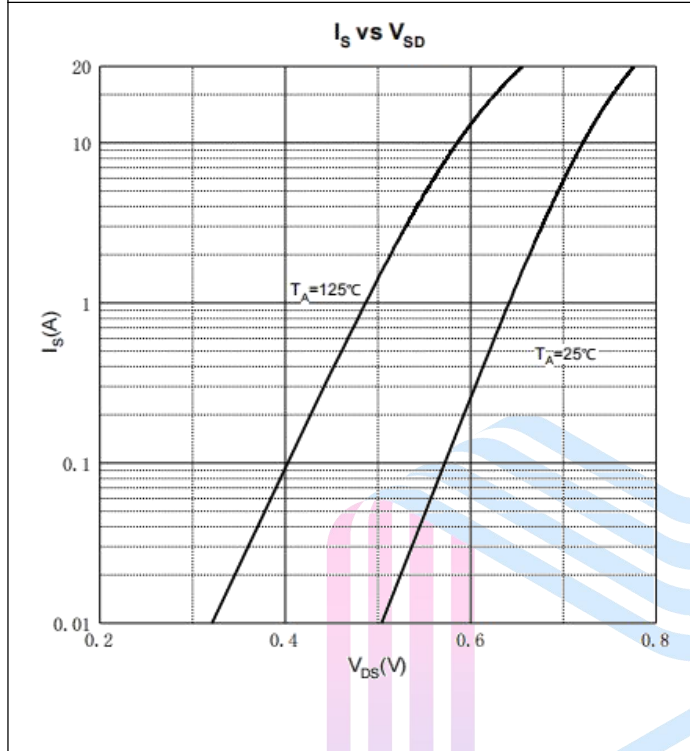
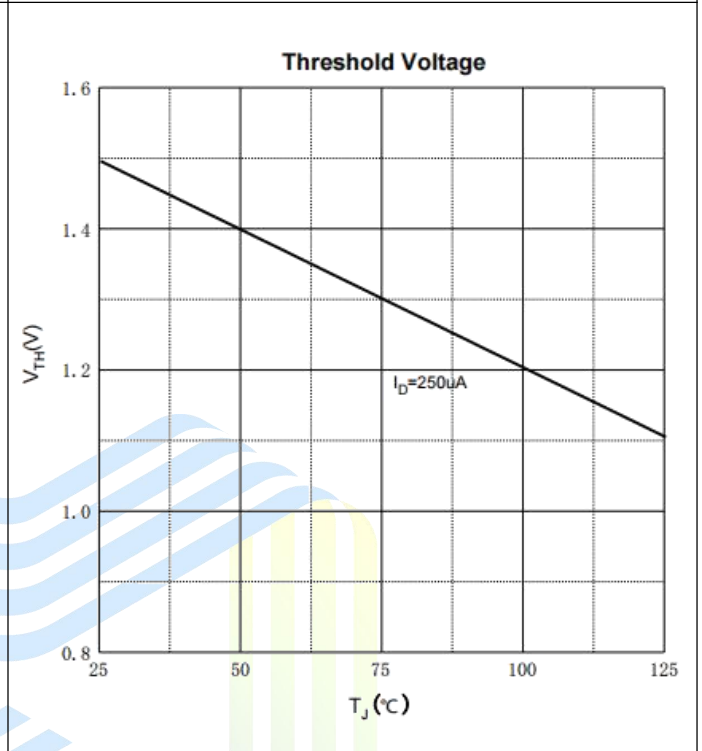
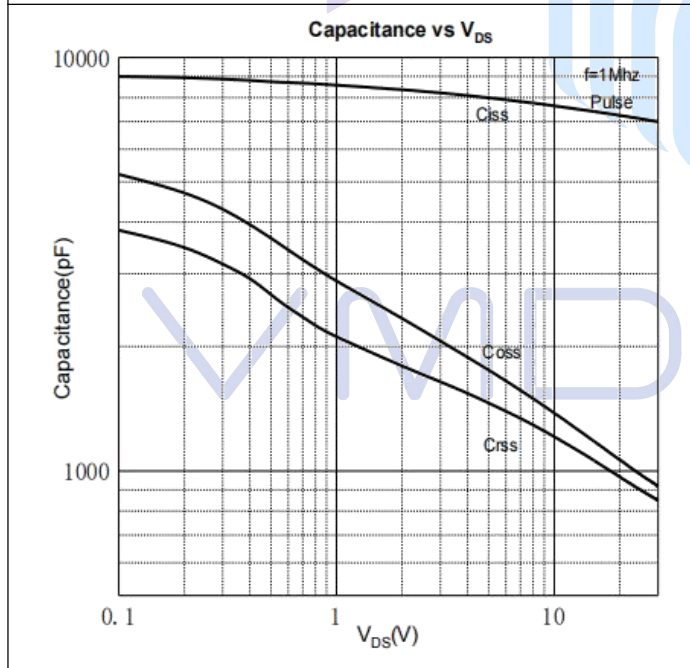
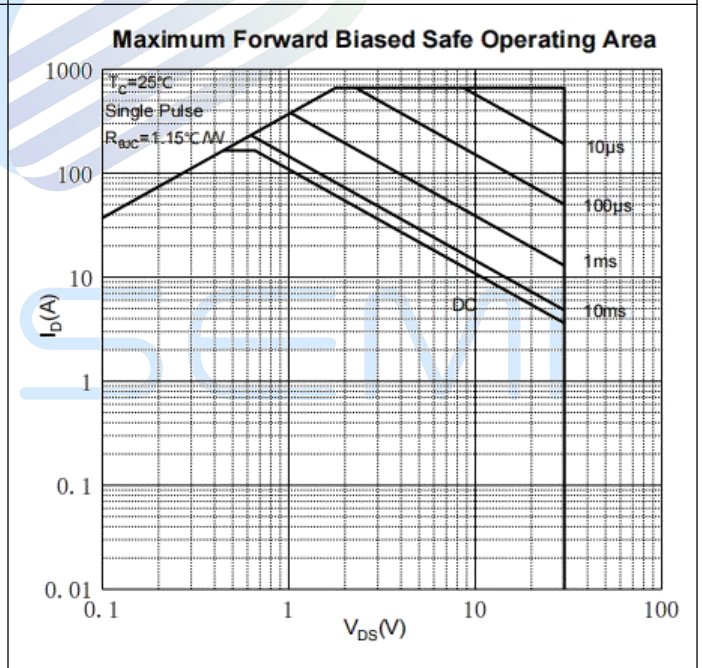
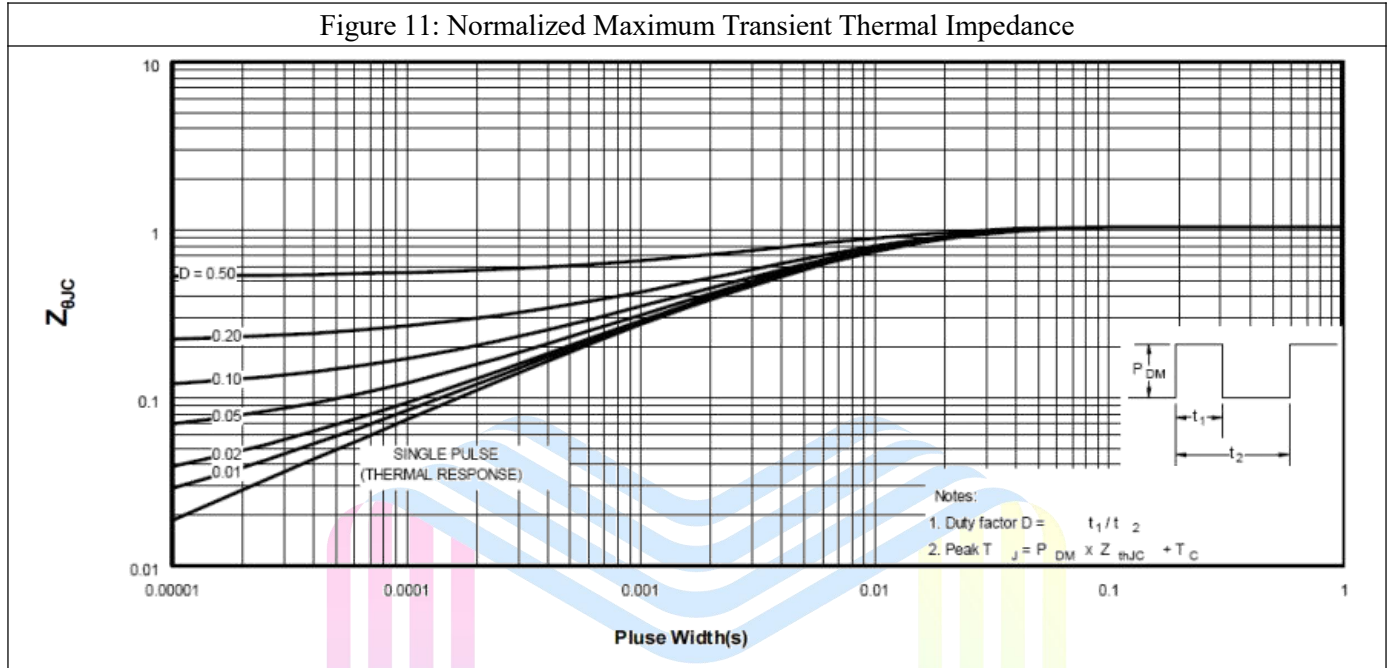
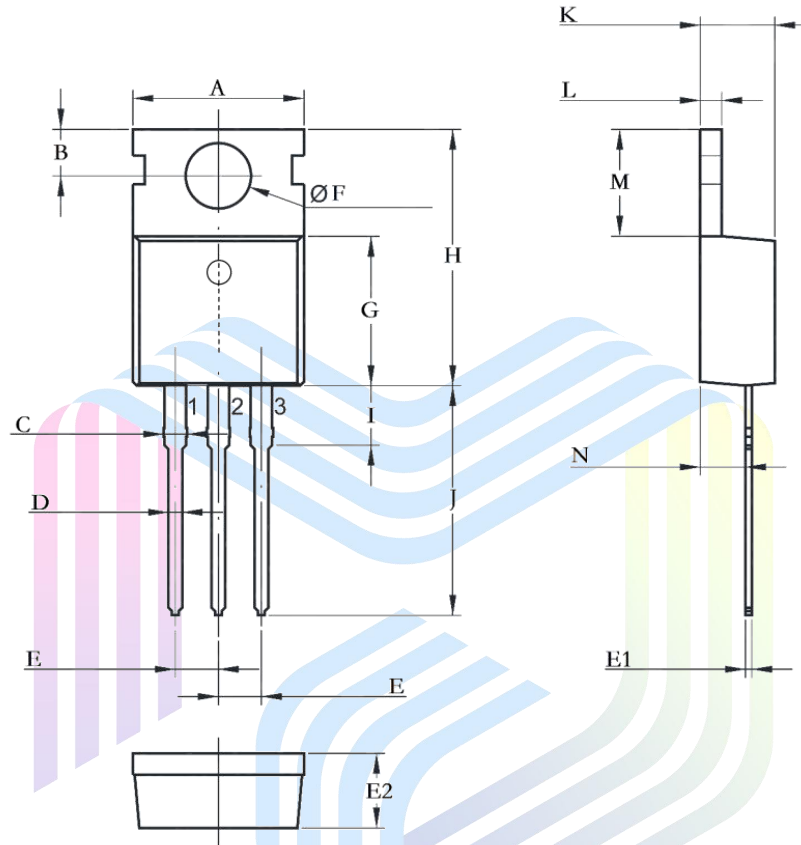
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operating Area


Figure 11: Normalized Maximum Transient Thermal Impedance


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Mechanical Dimensions:
TO-220-3L-C Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.600	10.400	0.378	0.409
B	2.800TYP		0.110TYP	
C	1.200	1.600	0.047	0.063
D	0.600	1.000	0.024	0.039
E	2.540TYP		0.100TYP	
E1	0.300	0.700	0.012	0.028
E2	4.300	4.700	0.169	0.185
F	3.400	4.000	0.134	0.157
G	8.850	9.350	0.348	0.368
H	14.600	16.100	0.575	0.634
I	2.800	4.200	0.110	0.165
J	12.600	14.800	0.496	0.583
K	4.300	4.700	0.169	0.185
L	1.000	1.400	0.039	0.055
M	5.840	7.000	0.230	0.276
N	1.800	2.900	0.071	0.114

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